INTEGRATED CIRCUITS



Product specification Supersedes data of 1995 Mar 22 File under Integrated Circuits, IC02 1996 Sep 24



FEATURES

- Complete 1.3 GHz single chip system
- Four PNP band switch buffers (40 mA)
- 33 V output tuning voltage
- In-lock detector
- 5-step ADC
- 15-bit programmable divider
- Programmable reference divider ratio (512, 640 or 1024)
- Programmable charge-pump current (60 or 280 μA)
- Programmable automatic charge-pump current switch
- Varicap drive disable
- Universal bus protocol I²C-bus or 3-wire bus:
 - bus protocol for 18 or 19 bits transmission (3-wire bus)
 - extra protocol for 27 bits for test and features (3-wire bus)
 - address plus 4 data bytes transmission (I²C-bus write mode)
 - address plus 1 status byte transmission (I²C-bus read mode)
 - three independent I²C-bus addresses
- Low power and low radiation.

ORDERING INFORMATION

		PACKAGE	
ITPE NUMBER	NAME	DESCRIPTION	VERSION
TSA5526M	SSOP16	plastic shrink small outline package; 16 leads; body width 4.4 mm	SOT369-1
TSA5526T	SO16	plastic small outline package; 16 leads; body width 3.9 mm	SOT109-1
TSA5527M	SSOP16	plastic shrink small outline package; 16 leads; body width 4.4 mm	SOT369-1
TSA5527T	SO16	plastic small outline package; 16 leads; body width 3.9 mm	SOT109-1
TSA5526AM	SSOP16	plastic shrink small outline package; 16 leads; body width 4.4 mm	SOT369-1
TSA5526AT	SO16	plastic small outline package; 16 leads; body width 3.9 mm	SOT109-1
TSA5527AM	SSOP16	plastic shrink small outline package; 16 leads; body width 4.4 mm	SOT369-1
TSA5527AT	SO16	plastic small outline package; 16 leads; body width 3.9 mm	SOT109-1

APPLICATIONS

- TV tuners and front ends
- VCR tuners.



TSA5526; TSA5527

QUICK REFERENCE DATA

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
V _{CC1}	supply voltage (+5 V)		4.5	-	5.5	V
V _{CC2}	band switch supply voltage (12 V)		V _{CC1}	12	13.5	V
I _{CC1}	supply current		-	20	25	mA
I _{CC2}	band switch supply current	note 1	-	50	55	mA
f _{RF}	RF input frequency		64	_	1300	MHz
V _{i(RF)}	RF input voltage	f _i = 80 to 150 MHz	-25	_	3	dBm
		f _i = 150 to 1000 MHz	-28	_	3	dBm
		$f_i = 1000$ to 1300 MHz	-15	_	3	dBm
f _{xtal}	crystal oscillator input frequency		3.2	4.0	4.48	MHz
I _{o(PNP)}	PNP band switch buffers output current	note 2	4	-	50	mA
P _{tot}	total power dissipation	note 3	-	250	400	mW
T _{stg}	storage temperature		-40	-	+150	°C
Tamb	operating ambient temperature		-20	-	+85	°C

Notes

1. One band switch buffer ON, $I_0 = 40$ mA.

2. One band switch buffer ON, $I_0 = 40$ mA; two buffers ON, maximum sum of $I_0 = 50$ mA.

3. The power dissipation is calculated as follows:

 $\mathsf{P}_{\mathsf{D}} = \mathsf{V}_{\mathsf{CC1}} \times \mathsf{I}_{\mathsf{CC1}} + \mathsf{V}_{\mathsf{CC2}} \times (\mathsf{I}_{\mathsf{CC2}} - \mathsf{I}_{\mathsf{o}}) + \mathsf{I}_{\mathsf{o}} \times \mathsf{V}_{\mathsf{CE}(\mathsf{satPNP})} + (\mathsf{V33}/2)^2/27 \mathrm{k}\Omega.$

TSA5526; TSA5527

1.3 GHz universal bus-controlled TV synthesizers

GENERAL DESCRIPTION

The device is a single-chip PLL frequency synthesizer designed for TV and VCR tuning systems. The circuit consists of a divide-by-eight prescaler with its own preamplifier, a 15-bit programmable divider, a crystal oscillator and its programmable reference divider and a phase/frequency detector combined with a charge-pump which drives the tuning amplifier and the 33 V output. Four high-current PNP band switch buffers are provided for band switching. Two PNP buffers can be switched on simultaneously. The sum of the collector currents is limited to 50 mA.

Depending on the reference divider ratio (512, 640 or 1024), the phase comparator operates at 3.90625 kHz, 6.25 kHz or 7.8125 kHz using a 4 MHz crystal.

The device can be controlled in accordance with the I²C-bus format or the 3-wire bus format depending on the voltage applied to the SW input (see Table 2). In the 3-wire bus mode (SW = HIGH) pin 12 is the LOCK output. The lock output is LOW when the PLL loop is locked. In the I²C-bus mode (SW = LOW) the LOCK detector bit FL is set to logic 1 when the loop is locked and is read on the SDA line (status byte) during a read operation. The ADC input is available on pin 12 for AFC control in the I²C-bus mode only. The ADC code is read during a read operation on the I²C-bus. In the test mode pin 12 is used as a test output for f_{ref} and ¹/₂f_{div} in the I²C-bus mode (see Table 6).

When the automatic charge-pump current switch mode is activated, depending on the device given in Table 6, and when the loop is phase-locked, the charge-pump current value is automatically switched to LOW. This action is taken to improve the carrier-to-noise ratio. The status of this feature can be read in the ACPS flag during a read operation on the I²C-bus (see Table 8).

I²C-bus format (SW = LOW)

Five serial bytes (including address byte) are required to address the device, select the VCO frequency, program the four PNP band switch buffers, set the charge-pump current and the reference divider ratio.

The device has three independent I²C-bus addresses which can be selected by applying a specific voltage on the CE input (see Table 5). The general address C2 is always valid. When the I²C-bus format is fully used, TSA5526 and TSA5527 are equal.

3-wire bus format (SW = V_{CC1} or open-circuit)

Data is transmitted to the device during a HIGH level on the CE input (enable line pin 15). The device is compatible with 18-bit and 19-bit data formats. The first four bits are used to program the PNP band switch buffers and the remaining bits are used to control the programmable divider. A 27-bit data format may also be used to set the charge-pump current, the reference divider ratio and for test purposes. The differences between TSA5526 and TSA5527 are given in Table 1.

When the 27-bit format is used, the TSA5526 and TSA5527 are equal and the reference divider is controlled by the RSA and RSB bits (see Table 7 and Figs 3, 4 and 5).

TYPE NUMBER	DATA WORD	REFERENCE DIVIDER	FREQUENCY STEP (kHz)
TSA5526	18-bit	512 ⁽¹⁾	62.5
TSA5526	19-bit	1024(1)	31.25
TSA5527	19-bit	640 ⁽²⁾	50

Table 1 Differences between TSA5526 and TSA5527

Notes

- 1. The selection of the reference divider is given by an automatic identification of the data word length.
- 2. The reference divider is set to 640 at power-on reset.

BLOCK DIAGRAM



P INN IN G

SYMBOL	PIN	DESCRIPTION
RF	1	RF signal input
V _{EE}	2	ground
V _{CC1}	3	supply voltage (+5 V)
V _{CC2}	4	band switch supply voltage (+12 V)
BS4	5	PNP band switch buffer output 4
BS3	6	PNP band switch buffer output 3
BS2	7	PNP band switch buffer output 2
BS1	8	PNP band switch buffer output 1
СР	9	charge-pump output
V _{tune}	10	tuning voltage output
SW	11	bus format selection input, I ² C-bus or 3-wire
LOCK/ADC	12	lock detector output (3-wire bus/ ADC input (I ² C-bus)
SCL	13	serial clock input
SDA	1 4	serial data input/output
CE	15	chip enable/address selection input
XTAL	16	crystal oscillator input

FUNCTIONAL DESCRIPTION

The device is controlled via the I²C-bus or the 3-wire bus depending on the voltage applied to the SW input (pin 11). A HIGH level on the SW input enables the 3-wire bus inputs which are CE (Chip Enable), SDA (serial data input) and SCL (serial clock input). A LOW level on the SW input enables the I²C-bus inputs which are AS (Address Selection input), SDA (serial data input/output) and SCL (serial clock input). The bus format selection is given in Table 2.

I²C-bus mode (SW = LOW); see Table 3

WRITE MODE $(\mathbf{R}/\mathbf{W} = 0)$

Data bytes can be sent to the device after the address transmission (first byte). Four data bytes are required to fully program the device. The bus transceiver has an auto-increment facility which permits the programming of the device within one single transmission (address + 4 data bytes).

The device can also be partially programmed providing that the first data byte following the address is Divider Byte 1 (DB1) or the Control Byte (CB). The bits in the data bytes are defined in Table 3.

TSA5526; TSA5527



The first bit of the first data byte transmitted indicates whether frequency data (first bit = logic 0) or control and band switch data (first bit = logic 1) will follow. Until an I²C-bus STOP command is sent by the controller, additional data bytes can be entered without the need to readdress the device. The frequency register is loaded after the 8th clock pulse of the second Divider Byte (DB2), the control register is loaded after the 8th clock pulse of the Control Byte (CB) and the band switch register is loaded after the 8th clock pulse of the Band switch Byte (BB).

I²C-BUS ADDRESS SELECTION

The module address contains programmable address bits (MA1 and MA0) which offer the possibility of having several synthesizers (up to 3) in one system by applying a specific voltage to the CE input.

The relationship between MA1 and MA0 and the input voltage applied to the CE input is given in Table 5.

TSA5526; TSA5527

Table 2 Bus format selection	on
------------------------------	----

PIN	NAME	3-WIRE BUS MODE	I ² C-BUS MODE
11	SW	OPEN or HIGH	LOW
12	LOCK/ADC	LOCK/TEST output	ADC input/TEST output
13	SCL	clock input	SCL input
14	SDA	data input	SDA input/output
15	CE	chip enable input	address selection input

Table 3 I²C-bus data format

BYTE	MSB		ΔΑΤΑ ΒΥΤΕ				LSB	SLAVE Answer	
Address Byte (ADB)	1	1	0	0	0	MA1	MA0	R/W = 0	А
Divider Byte 1 (DB1)	0	N14	N13	N12	N11	N10	N9	N8	А
Divider Byte 2 (DB2)	N7	N6	N5	N4	N3	N2	N1	N0	А
Control Byte (CB)	1	CP	T2	⊤1	T0	RSA	RSB	OS	А
Band switch Byte (BB)	Х	Х	Х	Х	BS4	BS3	BS2	BS1	А

Table 4Description of Table 3

SYMBOL DESCRIPTION			
Α	acknowledge		
MA1 and MA0	programmable address bits (see Table 5)		
N14 to N0	programmable divider bits; N = N14 × 2^{14} + N13 × 2^{13} + + N1 × 2 + N0		
СР	charge-pump current; $CP = 0 = 60 \mu A$; $CP = 1 = 280 \mu A$ (default)		
T2 to T0	test bits (see Table 6); for normal operation $T2 = 0$, $T1 = 0$ and $T0 = 1$ (default)		
RSA and RSB	reference divider ratio select bits (see Table 7)		
OS	tuning amplifier control bit; for normal operation $OS = 0$ and tuning voltage is ON (default); when $OS = 1$ tuning voltage is OFF (high impedance)		
BS4 to BS1	PNP band switch buffers control bits; when $BS_n = 0$ buffer n is OFF; when $BS_n = 1$ buffer n is ON		
Х	don't care		

Table 5 I²C-bus address selection

VOLTAGE APPLIED TO THE CE INPUT (SW = LOW)	MA1	M A O
0 V to 0.1V _{CC1}	0	0
Always valid	0	1
0.4V _{CC1} to 0.6V _{CC1}	1	0
0.9V _{CC1} to V _{CC1}	1	1

Product specification

1.3 GHz universal bus-controlled TV synthesizers

TSA5526; TSA5527

Table 6 Test bits

T2	T 1	TO	TSA5526; TSA5527	TSA5526A; TSA5527A	REMARKS
0	0	0	normal operation with automatic charge-pump switch ON	automatic charge-pump switch OFF	
0	0	1	normal operation with automatic charge-pump switch OFF	automatic charge-pump switch ON	status at POR
0	1	Х	charge-pump is OFF	charge-pump is OFF	
1	1	0	charge-pump is sinking current	charge-pump is sinking current	
1	1	1	charge-pump is sourcing current	charge-pump is sourcing current	
1	0	0	f _{ref} is available at LOCK output	f _{ref} is available at LOCK output	the ADC cannot be used when test mode is active
1	0	1	¹ ∕₂f _{div} is available at LOCK output	¹ / ₂ f _{div} is available at LOCK output	the ADC cannot be used when test mode is active

Table 7 Ratio select bits

RSA	RSB	REFERENCE DIVIDER
X	0	640
0	1	1024
1	1	512

READ MODE (R/W = LOGIC 1); see Table 8

Data can be read from the device by setting the R/W bit to logic 1. After the slave address has been recognized, the device generates an acknowledge pulse and the first data byte (status byte) is transferred on the SDA line (MSB first). Data is valid on the SDA line during a HIGH level of the SCL clock signal. A second data byte can be read from the device if the microcontroller generates an acknowledge on the SDA line (master acknowledge). End of transmission will occur if no master acknowledge occurs. The device will then release the data line to allow the microcontroller to generate a stop condition. The POR flag is set to logic 1 at power-on. The flag is reset when an end-of-data is detected by the device (end of a read sequence). Control of the loop is made possible with the in-lock flag (FL) which indicates when the loop is locked (FL = logic 1).

The Automatic Charge-Pump Switch flag (ACPS) is LOW when the automatic charge-pump switch mode is ON and the loop is locked. In other conditions ACPS = logic 1. When ACPS = logic 0, the charge-pump current is forced to the LOW value.

A built-in ADC is available at pin 12 (I²C-bus only). This converter can be used to apply AFC information to the microcontroller from the IF section of the television. The relationship between the bits A2 to A0 is given in Table 9.

Table 8	Read data format
---------	------------------

BYTE MSB Address Byte (ADB) 1				DATA		LSB	SLAVE Answer		
Address Byte (ADB)	1	1	0	0	0	MA1	MA0	R/W = 1	A ⁽¹⁾
Status Byte (SB)	POR ⁽²⁾	FL(3)	ACPS ⁽⁴⁾	1	1	A2 ⁽⁵⁾	A1 ⁽⁵⁾	A0 ⁽⁵⁾	-

Notes

- 1. A = acknowledge.
- 2. POR = power-on reset flag (POR = logic 1 at power-on).
- 3. FL = in-lock flag (FL = logic 1 when the loop is locked).
- 4. ACPS = automatic charge-pump switch flag (active ACPS = logic 0; non-active ACPS = logic 1).
- 5. A2 to A0 = digital outputs of the 5-level ADC.

VOLTAGE APPLIED AT ADC INPUT ⁽¹⁾	A2	A1	A0
0.6V _{CC1} to V _{CC1}	1	0	0
0.45V _{CC1} to 0.6V _{CC1}	0	1	1
0.3V _{CC1} to 0.45V _{CC1}	0	1	0
0.15V _{CC1} to 0.3V _{CC1}	0	0	1
0 to 0.15V _{CC1}	0	0	0

Table 9 ADC levels

Note

1. Accuracy is $\pm 0.03 V_{CC1}$.

3-wire bus mode (SW = open-circuit or V_{CC1}); see Figs 3, 4 and 5

During a HIGH level on the CE input, the data is clocked into the data register at the HIGH-to-LOW transition of the clock pulse. The first four bits control the band switch buffers and are loaded into the internal band switch register on the 5th rising edge of the clock pulse. The frequency bits are loaded into the frequency register at the HIGH-to-LOW transition of the chip enable line when an 18-bit or 19-bit data word is transmitted.

At power-on the charge-pump current is set to 280 $\mu A,$ the tuning voltage output is disabled (V_{tune} = 33 V in

Product specification

TSA5526; TSA5527

application; see Fig. 12), the test bits T2, T1 and T0 are set to the 0 0 1 state in the normal mode with ACPS OFF for TSA55226; TSA5527 and ACPS ON for TSA5526A; TSA5527A. RSB is set to logic 1 (TSA5526) or logic 0 (TSA5527). When an 18-bit data word is transmitted, the most significant bit of the divider N14 is internally set to logic 0 and bit RSA is set to logic 1. When a 19-bit data word is transmitted, bit RSA is set to logic 0.

When a 27-bit word is transmitted, the frequency bits are loaded into the frequency register on the 20th rising edge of the clock pulse and the control bits at the HIGH-to-LOW transition of the chip enable line. In this mode, the reference divider is given by the RSA and RSB bits (see Table 7). The test bits T2, T1 and T0, the charge-pump bit CP, the ratio select bit RSB and the OS bit can only be selected or changed with a 27-bit transmission. They remain programmed if an 18-bit or a 19-bit transmission occurs. Only RSA is controlled by the transmission length when the 18-bit or 19-bit format is used.

A data word of less than 18 bits will not affect the frequency register of the device. The definition of the bits is unchanged compared to the I²C-bus mode.

The power-on detection threshold voltage V_{POR} is fixed to $V_{CC1} = 2$ V at room temperature. Below this threshold, the device is reset to the power-on state previously described.







Product specification

1.3 GHz universal bus-controlled TV synthesizers

TSA5526; TSA5527

LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 134).

SYMBOL	PARAMETER	MIN.	MAX.	UNIT
V _{CC1}	supply voltage; +5 V (pin 3)	-0.3	+6.0	V
V _{CC2}	band switch supply voltage; +12 V (pin 4)	-0.3	+16	V
V _{i(RF)}	prescaler input voltage (pin 1)	-0.3	V _{CC1}	V
V _{o(BSn)}	band switch buffers output voltage (pins 5 to 8)	-0.3	V _{CC2}	V
I _{o(BSn)}	band switch buffers output current	-1	+50	mA
V _{o(CP)}	charge-pump output voltage (pin 9)	-0.3	V _{CC1}	V
V _{o(tune)}	output tuning voltage (pin 10)	-0.3	+35	V
V _{i(SW)}	input switching voltage (pin 11)	-0.3	V _{CC1}	V
V _{o(LOCK)}	lock output voltage (pin 12)	-0.3	V _{CC1}	V
V _{i(SCL)}	serial clock input voltage (pin 13)	-0.3	+6.0	V
V _{i/o(SDA)}	serial data input/output voltage (pin 14)	-0.3	+6.0	V
I _{o(SDA)}	serial data output current	-1	+10	mA
V _{i(CE)}	chip enable input voltage (pin 15)	-0.3	+6.0	V
V _{i(xtal)}	crystal oscillator input voltage (pin 16)	-0.3	V _{CC1}	V
T _{stg}	storage temperature	-40	+150	°C
Tj	maximum junction temperature	-	+150	°C
t _{sc}	short-circuit time; every pin except pin 4 to pin 3 and every pin to pin 2; note 1	-	10	s

Note

1. Short-circuit between V_{CC1} and V_{CC2} is allowed provided the voltage applied to V_{CC2} is less than the 6 V maximum rating at V_{CC1} .

THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	VALUE	UNIT
R _{th j-a}	thermal resistance from junction to ambient in free air		
	SO16	110	K/W
	SSOP16	142	K/W

HANDLING

Inputs and outputs are protected against electrostatic discharge in normal handling. However, to be totally safe, it is desirable to take normal precautions appropriate to handling bipolar devices. Every pin withstands the ESD test in accordance with "*MIL-STD-883C*" category B (2000 V). Every pin withstands the ESD test in accordance with Philips Semiconductors Machine Model 0 Ω , 200 pF (200 V).

TSA5526; TSA5527

CHARACTERISTICS

 V_{CC1} = 4.5 to 5.5 V; V_{CC2} = V_{CC1} to 13.2 V; T_{amb} = -20 to +85 °C; unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
Supplies	-					1
V _{CC1}	supply voltage		4.5	-	5.5	V
V _{CC2}	band switch buffers supply voltage		V _{CC1}	-	13.5	V
I _{CC1}	supply current	at power-on	-	20	25	mA
I _{CC2}	band switch buffers supply current	at power-on	-	0.5	1.0	mA
		one band switch buffer is ON; I _{source} = 40 mA	-	50	55	mA
		two band switch buffers are ON; I _{source} = 40 mA + 5 mA (any combination)	-	56	62	mA
V _{POR}	supply voltage below which POR is active		1.5	2.0	_	V
f _{RF}	RF input frequency		64	-	1300	MHz
DR	divider ratio	15-bit frequency word	256	-	32767	
		14-bit frequency word	256	-	16383	
f _{xtal}	crystal oscillator input frequency	$R_{xtal} = 25$ to 300 Ω	3.2	4	4.48	MHz
Z _{xtal}	crystal oscillator input impedance (absolute value)	$\mathfrak{f}_i=4\ MHz$	600	1 200	-	Ω
Prescaler	(see Figs 6 an d 7)					
V _{i(RF)}	RF input level	f _i = 80 to 150 MHz	-25	-	3	dBm
		f _i = 150 to 1000 MHz	-28	-	3	dBm
		$f_i = 1000$ to 1300 MHz	-15	-	3	dBm
Z _{i(RF)}	input impedance	see Fig.8				
PNP band	switch buffers outputs (pins 5 to 8)					
I _{LO}	output leakage current	$\label{eq:V_GC2} \begin{array}{l} V_{GC2} = 13.5 \ V; \\ V_o = 0 \ V \end{array}$	-10	-	-	μA
V _{o(sat)}	output saturation voltage	$ I_{source} = 40 \text{ mA}; V_{o(sat)} = V_{CC2} - V_o $	-	0.2	0.4	V
LOCK out	put (PNP collector output) 3 wire bus mo	de (pin 12)				
I _{o(ool)}	output current when out-of-lock	$V_{CC1} = 5.5 \text{ V}; V_0 = 5.5 \text{ V}$	-	-	100	μA
V _{osat(ool)}	output saturation voltage when out-of-lock	$ I_{source} = 200 \ \mu\text{A}; \\ V_{o(sat)} = V_{CC1} - V_{o} $	-	0.4	0.8	V
V _{o(LOCK)}	lock output voltage		-	0.01	0.4	V
ADC input	; (I ² C-bus mode) pin 12					
V _{i(ADC)}	ADC input voltage	see Table 9	0	-	V _{CC1}	V
I _{IH(ADC)}	HIGH level input current	$V_{ADC} = V_{CC1}$	-	-	10	μA
IIL(ADC)	LOW level input current	$V_{ADC} = 0 V$	-1 0	-	_	μA

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
SW input (bus form at switch)		1	1		4
VIL	LOW level input voltage		0	-	1.5	V
VIH	HIGH level input voltage		3	-	V _{CC1}	V
I _{IH}	HIGH level input current	$V_{SW} = V_{CC1}$	-	-	10	μA
IIL	LOW level input current	$V_{SW} = 0 V$	-100	-	-	μA
CE input (chip enable/address selection)					
VIL	LOW level input voltage		0	-	1.5	V
VIH	HIGH level input voltage		3	-	5.5	V
I _{IH}	HIGH level input current	V _{CE} = 5.5 V	-	-	10	μA
կլ	LOW level input current	$V_{CE} = 0 V$	- 1 0	-	-	μA
SCL and S	DA inputs					
VIL	LOW level input voltage		0	-	1.5	V
VIH	HIGH level input voltage		3.0	-	5.5	V
I _{IH}	HIGH level input current	$V_{BUS} = 5.5 \text{ V}; V_{CC1} = 0 \text{ V}$	-	-	10	μA
		$V_{BUS} = 5.5 \text{ V}; V_{CC1} = 5.5 \text{ V}$	-	-	10	μA
IIL	LOW level input current	$V_{BUS} = 1.5 \text{ V}; V_{CC1} = 0 \text{ V}$	-	-	10	μA
		$V_{BUS} = 0 V; V_{CC1} = 5.5 V$	-1 0	-	-	μA
f _{clk}	clock frequency		-	100	400	kHz
SDA outpu	uts (I ² C-bus mode)					
I _{LO}	output leakage current	$V_{SDA} = 5.5 V$	-	-	10	μA
Vo	output voltage	I _{sink} = 3 mA	-	-	0.4	V
Charge-pu	mp output CP					÷
II _{ICPH}	HIGH charge-pump current	CP = 1	-	280	-	μA
I _{ICPL}	LOW charge-pump current	CP = 0	-	60	-	μA
V _{CP}	output voltage	in-lock; T _{amb} = 25 °C	-	1.95	_	V
I _{LI(off)}	off-state leakage current	T2 = 0; T1 = 1	-15	-0.5	+15	nA
Tuning vol	ltage output V _{tune}					
I _{LO(off)}	leakage current when switched-off	$OS = 1$; $V_{tune} = 33 V$	-	-	10	μA
Vo	output voltage when the loop is closed	$ \begin{array}{l} OS = 0; \mbox{$T2$} = 0; \mbox{$T1$} = 0; \\ T0 = 1; \mbox{R_L} = 27 \ \mbox{k}\Omega; \\ V_{tune} = 33 \ \mbox{V} \end{array} $	0.2	-	32.7	V
3-wire bus	timing (see Figs 6 and 7)					
tніgн	clock high time		2	-	-	μs
ŧsu;dat	data set-up time		2	-	-	μs
ŧhd;dat	data hold time		2	-	-	μs
t _{SU;ENSCL}	enable to clock set-up time		1 0	-	-	μs
t _{HD;ENDAT}	enable to data hold time		2	-	_	μs
t _{EN}	enable between two transmissions		1 0	-	-	μs
thd;enscl	enable to clock active edge hold time		6	-	-	μs









TSA5526; TSA5527

INTERNAL PIN CONFIGURATION



TSA5526; TSA5527

1.3 GHz universal bus-controlled TV synthesizers

APPLICATION INFORMATION

Tuning amplifier

The tuning amplifier is capable of driving the varicap voltage without an external transistor. The tuning voltage output must be connected to an external load of 27 k Ω which is connected to the tuning voltage supply rail. Figs 11 and 12 show a possible loop filter. The component values depend on the oscillator characteristics and the selected reference frequency.

Crystal oscillator

The crystal oscillator uses a 4 MHz crystal connected in series with an 18 pF capacitor thereby operating in the series resonance mode. Connecting the oscillator to the supply voltage is preferred but it can, however, also be connected to ground.

Examples of I²C-bus sequences (SW = LOW)

Tables 10 to 14 show the various sequences where $f_{osc} = 100 \text{ MHz}$, BS4 = ON, $I_{GP} = 280 \mu A$, N = 512, $f_{xtal} = 4 \text{ MHz}$, S = START, A = acknowledge and P = STOP. The sequence is as follows:

START + address byte + divider byte 1 + divider byte 2 + control byte + band switch byte + STOP.

For the complete sequence see Table 10 (sequence 1) or Table 11 (sequence 2).

Table 10 Complete sequence 1

S	C2	A	06	A	40	A	CE	A	08	A	P
able 11	Complete	sequence	e 2								
S	C2	A	CE	Α	08	Α	06	A	40	Α	Р
able 12	Divider by	/tes only s	equence								
S		C2	A		06	Α		40	A		Ρ
	Control a		A witch byte A	s only sec		A		40 08	A		P
able 13 S	Control ar	nd band sv C2	witch byte A	s only sec	luence						

Table 15 One status byte acquisition

S C3 A XX ⁽¹⁾	X ⁽²⁾	Р
--------------------------	------------------	---

Notes

1. XX = the read status byte.

2. X = no acknowledge from the master means end of sequence.

Table 16 Two status byte acquisition

S C3 A XX ⁽¹⁾ A XX ⁽¹⁾ X ⁽²⁾ P								
	S	63	А	XX ⁽¹⁾	A	XX ⁽¹⁾	X ⁽²⁾	Р

Notes

- 1. XX = the read status byte.
- 2. X = no acknowledge from the master means end of sequence.

Other I²C-bus addresses may be selected by applying an appropriate voltage to the CE input.

Examples of 3-wire bus sequences (TSA5526; SW = OPEN)

Table 17 18-bit sequence ($f_{osc} = 800 \text{ MHz}$, BS4 = ON)

1	0	0	0	1	1	0	0	1	0	0	0	0	0	0	0	0	0

The reference divider is automatically set to 512 unless RSB has been programmed to 0 during a 27-bit sequence (see Table 19).

Table 18 19-bit sequence ($f_{osc} = 650$ MHz, BS3 = ON)

0 1 0 0 1 0 1 0 1 0 0 0 0 0 0 0 0 0 0 0																			
								~			•	-	•	~	-		~		
	0	1	0	0	1	0	1	0	0	0	1	0	1	0	0	0	0	0	(0)
	0	•	U V	U U		v	· ·	~	v	U U	•	v	· ·	v		U U	- V	~	Ŭ

The reference divider is automatically set to 1024 unless RSB has been programmed to 0 during a 27-bit sequence (see Table 19).

Table 19 27-bit sequence ($f_{osc} = 750$ MHz, BS1 = ON, N = 640, $I_{cp} = 60 \mu$ A, no test function)

0	0	0	1	0	1	1	1	0	1	0	1	0	0	1	1	0	0	0	1	0	0	0	1	0	0	0

Table 2019-bit sequence

		~
0 0	/ U	0
	-	-

This sequence will program f_{osc} to 600 MHz in 50 kHz steps. I_{CP} remains at 60 μ A.

Table 21 18-bit sequence

- [0	0	Δ	 1	0	-	- 4	1	Ω		1	4	Ω	Ω	0	0	0
	U	0	U	1	U			1	U	1			0	0	0	0	0
1																	

This sequence will program f_{osc} to 600 MHz in 50 kHz steps. I_{CP} remains at 60 μ A.

Table 22 27-bit sequence ($f_{osc} = 650 \text{ MHz}, \text{BS1} = \text{ON}$)

This sequence sets RSA to 0, RSB to 1 and CP to 1. After this sequence $I_{CP} = 280 \ \mu$ A, N = 1024 (19-bit transmission) and N = 512 (18-bit transmission), RSB = 1.

TSA5526; TSA5527

Example of 3-wire bus sequence (TSA5527; SW = OPEN)



_																			
	~		~		~			~		•	~		~					~	
	n I	1	n	1 0	0	1	1	I 0	1	1	0	1	L 0	1	1	I 0 -	I 0	0	I 0 I
	~		0		0	•		U U	•		U U			•				0	

N = 640 unless RSB has been programmed to 0 during a 27-bit sequence.





TSA5526; TSA5527

1.3 GHz universal bus-controlled TV synthesizers

PACKAGE OUTLINES

SO16: plastic small outline package; 16 leads; body width 3.9 mm



SOT109-1



TSA5526; TSA5527

SOLDERING

Introduction

There is no soldering method that is ideal for all IC packages. Wave soldering is often preferred when through-hole and surface mounted components are mixed on one printed-circuit board. However, wave soldering is not always suitable for surface mounted ICs, or for printed-circuits with high population densities. In these situations reflow soldering is often used.

This text gives a very brief insight to a complex technology. A more in-depth account of soldering ICs can be found in our "*IC Package Databook*" (order code 9398 652 90011).

Reflow soldering

Reflow soldering techniques are suitable for all SO packages.

Reflow soldering requires solder paste (a suspension of fine solder particles, flux and binding agent) to be applied to the printed-circuit board by screen printing, stencilling or pressure-syringe dispensing before package placement.

Several techniques exist for reflowing; for example, thermal conduction by heated belt. Dwell times vary between 50 and 300 seconds depending on heating method. Typical reflow temperatures range from 215 to 250 °C.

Preheating is necessary to dry the paste and evaporate the binding agent. Preheating duration: 45 minutes at 45 °C.

Wave soldering

Wave soldering techniques can be used for all SO packages if the following conditions are observed:

- A double-wave (a turbulent wave with high upward pressure followed by a smooth laminar wave) soldering technique should be used.
- The longitudinal axis of the package footprint must be parallel to the solder flow.
- The package footprint must incorporate solder thieves at the downstream end.

During placement and before soldering, the package must be fixed with a droplet of adhesive. The adhesive can be applied by screen printing, pin transfer or syringe dispensing. The package can be soldered after the adhesive is cured.

Maximum permissible solder temperature is 260 °C, and maximum duration of package immersion in solder is 10 seconds, if cooled to less than 150 °C within 6 seconds. Typical dwell time is 4 seconds at 250 °C.

A mildly-activated flux will eliminate the need for removal of corrosive residues in most applications.

Repairing soldered joints

Fix the component by first soldering two diagonallyopposite end leads. Use only a low voltage soldering iron (less than 24 V) applied to the flat part of the lead. Contact time must be limited to 10 seconds at up to 300 °C. When using a dedicated tool, all other leads can be soldered in one operation within 2 to 5 seconds between 270 and 320 °C.

TSA5526; TSA5527

DEFINITIONS

Data sheet status									
Objective specification This data sheet contains target or goal specifications for product development.									
Preliminary specification This data sheet contains preliminary data; supplementary data may be published later.									
Product specification This data sheet contains final product specifications.									
Limiting values									
more of the limiting values n of the device at these or at a	accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or hay cause permanent damage to the device. These are stress ratings only and operation any other conditions above those given in the Characteristics sections of the specification miting values for extended periods may affect device reliability.								
Application information									

Where application information is given, it is advisory and does not form part of the specification.

LIFE SUPPORT APPLICATIONS

These products are not designed for use in life support appliances, devices, or systems where malfunction of these products can reasonably be expected to result in personal injury. Philips customers using or selling these products for use in such applications do so at their own risk and agree to fully indemnify Philips for any damages resulting from such improper use or sale.

PURCHASE OF PHILIPS I²C COMPONENTS



Purchase of Philips I²C components conveys a license under the Philips' I²C patent to use the components in the I²C system provided the system conforms to the I²C specification defined by Philips. This specification can be ordered using the code 9398 393 40011.

TSA5526; TSA5527

NOTES

TSA5526; TSA5527

NOTES

TSA5526; TSA5527

NOTES

Philips Semiconductors – a worldwide company

Argentina: see South America Australia: 34 Waterloo Road, NORTH RYDE, NSW 2113, Tel. +61 2 9805 4455. Fax. +61 2 9805 4466 Austria: Computerstr. 6, A-1101 WIEN, P.O. Box 213, Tel. +43 1 60 101. Fax. +43 1 60 101 1210 Belarus: Hotel Minsk Business Center, Bld. 3, r. 1211, Volodarski Str. 6, 220050 MINSK, Tel. +375 172 200 733, Fax. +375 172 200 773 Belgium: see The Netherlands Brazil: see South America Bulgaria: Philips Bulgaria Ltd., Energoproject, 15th floor, 51 James Bourchier Blvd., 1407 SOFIA Tel. +359 2 689 211, Fax. +359 2 689 102 Canada: PHILIPS SEMICONDUCTORS/COMPONENTS. Tel. +1 800 234 7381 China/Hong Kong: 501 Hong Kong Industrial Technology Centre, 72 Tat Chee Avenue, Kowloon Tong, HONG KONG, Tel. +852 2319 7888. Fax. +852 2319 7700 Colombia: see South America Czech Republic: see Austria Denmark: Prags Boulevard 80, PB 1919, DK-2300 COPENHAGEN S, Tel. +45 32 88 2636, Fax. +45 31 57 1949 Finland: Sinikalliontie 3, FIN-02630 ESPOO. Tel. +358 615 800, Fax. +358 615 80920 France: 4 Rue du Port-aux-Vins, BP317, 92156 SURESNES Cedex, Tel. +33 1 40 99 6161, Fax. +33 1 40 99 6427 Germany: Hammerbrookstraße 69, D-20097 HAMBURG, Tel. +49 40 23 53 60, Fax. +49 40 23 536 300 Greece: No. 15, 25th March Street, GR 17778 TAVROS, Tel. +30 1 4894 339/911, Fax. +30 1 4814 240 Hungary: see Austria India: Philips INDIA Ltd, Shivsagar Estate, A Block, Dr. Annie Besant Rd. Worli, MUMBAI 400 018, Tel. +91 22 4938 541, Fax. +91 22 4938 722 Indonesia: see Singapore Ireland: Newstead, Clonskeadh, DUBLIN 14 Tel. +353 1 7640 000, Fax. +353 1 7640 200 Israel: RAPAC Electronics, 7 Kehilat Saloniki St, TEL AVIV 61180, Tel. +972 3 645 0444, Fax. +972 3 649 1007 Italy: PHILIPS SEMICONDUCTORS, Piazza IV Novembre 3, 20124 MILANO, Tel. +39 2 6752 2531, Fax. +39 2 6752 2557 Japan: Philips Bldg 13-37, Kohnan 2-chome, Minato-ku, TOKYO 108, Tel. +81 3 3740 5130, Fax. +81 3 3740 5077 Korea: Philips House, 260-199 Itaewon-dong, Yongsan-ku, SEOUL, Tel. +82 2 709 1412, Fax. +82 2 709 1415 Malaysia: No. 76 Jalan Universiti, 46200 PETALING JAYA, SELANGOR,

Tel. +60 3 750 5214, Fax. +60 3 757 4880 Mexico: 5900 Gateway East, Suite 200, EL PASO, TEXAS 79905,

Tel. +9-5 800 234 7381

Middle East: see Italy

Netherlands: Postbus 90050, 5600 PB EINDHOVEN, Bldg. VB, Tel. +31 40 27 82785, Fax. +31 40 27 88399

New Zealand: 2 Wagener Place, C.P.O. Box 1041, AUCKLAND, Tel. +64 9 849 4160, Fax. +64 9 849 7811

Norway: Box 1, Manglerud 0612, OSLO, Tel. +47 22 74 8000, Fax. +47 22 74 8341

Philippines: Philips Semiconductors Philippines Inc., 106 Valero St. Salcedo Village, P.O. Box 2108 MCC, MAKATI, Metro MANILA, Tel. +63 2 816 6380, Fax. +63 2 817 3474

Poland: UI. Lukiska 10, PL 04-123 WARSZAWA, Tel. +48 22 612 2831, Fax. +48 22 612 2327

Portugal: see Spain

Romania: see Italy

Russia: Philips Russia, UI. Usatcheva 35A, 119048 MOSCOW, Tel. +7 095 926 5361, Fax. +7 095 564 8323

Singapore: Lorong 1, Toa Payoh, SINGAPORE 1231, Tel. +65 350 2538, Fax. +65 251 6500

Slovakia: see Austria

Slovenia: see Italy

South Africa: S.A. PHILIPS Pty Ltd., 195-215 Main Road Martindale, 2092 JOHANNESBURG, P.O. Box 7430 Johannesburg 2000, Tel. +27 11 470 5911, Fax. +27 11 470 5494

South America: Rua do Rocio 220, 5th floor, Suite 51, 04552-903 São Paulo, SÃO PAULO - SP, Brazil, Tel. +55 11 821 2333, Fax. +55 11 829 1849

Spain: Balmes 22, 08007 BARCELONA, Tel. +34 3 301 6312, Fax. +34 3 301 4107

Sweden: Kottbygatan 7, Akalla, S-16485 STOCKHOLM, Tel. +46 8 632 2000, Fax. +46 8 632 2745

Switzerland: Allmendstrasse 140, CH-8027 ZÜRICH, Tel. +41 1 488 2686, Fax. +41 1 481 7730

Taiwan: PHILIPS TAIWAN Ltd., 23-30F, 66, Chung Hsiao West Road, Sec. 1, P.O. Box 22978, TAIPEI 100, Tel. +886 2 382 4443, Fax. +886 2 382 4444

Thailand: PHILIPS ELECTRONICS (THAILAND) Ltd., 209/2 Sanpavuth-Bangna Road Prakanong, BANGKOK 10260, Tel. +66 2 745 4090, Fax. +66 2 398 0793

Turkey: Talatpasa Cad. No. 5, 80640 GÜLTEPE/ISTANBUL, Tel. +90 212 279 2770, Fax. +90 212 282 6707

Ukraine: PHILIPS UKRAINE, 4 Patrice Lumumba str., Building B, Floor 7, 252042 KIEV, Tel. +380 44 264 2776, Fax. +380 44 268 0461

United Kingdom: Philips Semiconductors Ltd., 276 Bath Road, Hayes,

MIDDLESEX UB3 5BX, Tel. +44 181 730 5000, Fax. +44 181 754 8421

United States: 811 East Arques Avenue, SUNNYVALE, CA 94088-3409, Tel. +1 800 234 7381

Uruguay: see South America

Vietnam: see Singapore

Yugoslavia: PHILIPS, Trg N. Pasica 5/v, 11000 BEOGRAD, Tel. +381 11 825 344, Fax.+381 11 635 777

For all other countries apply to: Philips Semiconductors, Marketing & Sales Communications, Building BE-p, P.O. Box 218, 5600 MD EINDHOVEN, The Netherlands, Fax. +31 40 27 24825

Internet: http://www.semiconductors.philips.com

SCA51

© Philips Electronics N.V. 1996

All rights are reserved. Reproduction in whole or in part is prohibited without the prior written consent of the copyright owner.

The information presented in this document does not form part of any quotation or contract, is believed to be accurate and reliable and may be changed without notice. No liability will be accepted by the publisher for any consequence of its use. Publication thereof does not convey nor imply any license under patent- or other industrial or intellectual property rights.

Printed in The Netherlands

537021/50/02/pp28

Date of release: 1996 Sep 24

Document order number: 9397 750 01258

els make thi

Philips Semiconductors



